

2008 IEEE Workshop on Microelectronics and Electron Devices (WMED)

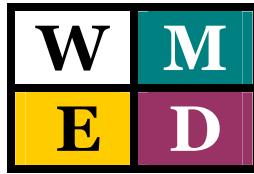


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April 18th, 2008

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